THERMINIC 2026

CALL FOR PAPERS
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THERMINIC 2026

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The 32nd THERMINIC Workshop will be held in Berlin, Germany. THERMINIC is the major European Workshop related to thermal and reliability issues in electronic components and systems. For academics and industrialists involved in micro- and power-electronics this annual event promises to be a very special occasion with a high quality technical programme and exciting social events. We invite delegates to consider submitting abstracts that are related, but not limited to, the following topics:

Thermal Phenomena in Simulation & Experiment:
- Thermal management of electronic components and systems
- Classical and modern thermometry and thermography
- Thermal interface materials and their characterisation
- Thermal modelling and investigation of packages
- Nano-scale heat transfer
- Multi-physics simulation and field coupling
- Electro-thermal modelling and simulation
- CFD modelling and benchmarking
- Advanced thermal materials and technologies
- Numerical methods for multi-scale heat transfer
- Advanced mathematics and statistical concepts / AI methods for digital twins

Electronics Cooling Concepts & Applications:
- Cooling concepts: air, liquid, 2-phase, etc.
- Power electronics cooling technologies
- HPC & chiplet cooling
- High temperature electronics

- Solid state lighting & LED packages
- Thermo-electric and sub-ambient cooling
- Novel and advanced thermal technologies
- Heat pipe and vapor chambers
- 3D heterogeneous integration and cooling
- Ultra low form factor air cooling
- Novel manufacturing methods
- Cooling for IoT, CPS, mobile, edge computing
- Thermal buffering for computational sprinting
- Thermal management for quantum technologies & cryo-applications
- Battery thermal management

Thermo-Mechanical Reliability:
- Thermo-mechanical reliability
- Prognostics and health monitoring
- Lifetime modelling and prediction
- Damage and fracture mechanics
- Failure analysis and inline inspection

Please submit your abstract via our online system, which will open in December 2025.

The technical programme will include oral talks, poster presentations, special sessions and invited keynote talks given by renowned speakers. We will again offer a professional development course (PDC) on the day before the workshop.

Authors are invited to submit an abstract describing recent work. Abstracts must detail the objectives of the work presented and demonstrate new results. All abstracts will undergo a double-blind review process. There will be best paper and best poster awards.

Please, refer to the www.therminic.eu web page for information on past THERMINIC workshops. Accepted papers will be submitted for inclusion into IEEE Xplore and be subject to meeting IEEE Xplore's scope and quality requirements. THERMINIC papers can be searched through IEEE, Google scholar and other search engines. Vendors and Book Exhibitors are invited to offer products at the Workshop. Exhibitor space is available – please contact the local organizing committee for further details. Editors are invited to exhibit books.

Deadline abstract submission:	**April 1, 2026**
Notification of acceptance:	**June 8, 2026**
Submission of paper for workshop proceedings:	**August 3, 2026**

Venue
NYX Hotel Berlin Köpenick
Grünauer Str. 1, 12557 Berlin
Germany

Contact
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